

F Highlight all hit terms in red.

April 2004

#	#-1	Inventor	Document#	Issue #	Title	Current	Current XR	Retrieval	S	C	P	3	Image	Doc.	P
1		Andideh, Ebra	US 2004004	200409	Carbon doped oxide deposition	438/232			R	R	R	R	C	US 2004004	
2		Andideh, Ebra	US 2003007	200309	Carbon doped oxide deposition	438/780	257/E21.27		R	R	R	R	C	US 2003007	
3		Andideh, Ebra	US 6877253	200408	Carbon doped oxide deposition	438/784	257/E21.27		R	R	R	R	C	US 6877253	
4		Yin, Ziping e	US 2003020	200311	Low k film application for interlevel dielectri	438/200			R	R	R	R	C	US 2003020	
5		Yin, Ziping e	US 2003020	200311	Low k film application for interlevel dielectri	257/639			R	R	R	R	C	US 2003020	
6		Bao, Tian1 et	US 2003020	200318	Method for forming a carbon doped oxide lo	438/783	438/823		R	R	R	R	C	US 2003020	
7		Yin, Ziping e	US 2003010	200301	LOW K FILM APPLICATION FOR INTERLEVEL	257/639			R	R	R	R	C	US 2003010	
8		Yin, Ziping e	US 6805883	200301	Low k film application for interlevel dielectri	257/839	438/751		R	R	R	R	C	US 6805883	
9		Catabay, Wfi	US 6492731	200219	Composite low dielectric constant film for in	257/758	257/411		R	R	R	R	C	US 6492731	
10		Choi, Simon	US 6436824	200208	Low dielectric constant materials for copper	438/687	257/E21.26		R	R	R	R	C	US 6436824	